# **Switching Transistor**

# **NPN Silicon**

#### Features

• These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V <sub>CEO</sub>	40	Vdc
Collector – Base Voltage	V <sub>CBO</sub>	60	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	6.0	Vdc
Collector Current – Continuous	۱ <sub>C</sub>	600	mAdc
Collector Current – Peak	I <sub>CM</sub>	900	mAdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) @T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate (Note 2) @T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

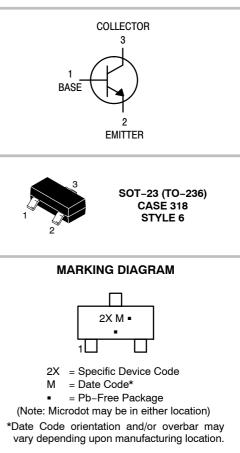
\*Transient pulses must not cause the junction temperature to be exceeded. 1. FR-5 =  $1.0 \times 0.75 \times 0.062$  in.

2. Alumina = 0.4  $\times$  0.3  $\times$  0.024 in. 99.5% alumina.



## **ON Semiconductor®**

http://onsemi.com



#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMBT4401LT1G	SOT-23 (Pb-Free)	3000 Tape & Reel
MMBT4401LT3G	SOT-23 (Pb-Free)	10,000 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Cha	Symbol	Min	Max	Unit		
OFF CHARACTERISTICS						
Collector – Emitter Breakdown Voltage	e (Note 3) (I <sub>C</sub> = 1.0 mAdc, I <sub>B</sub> = 0)	V <sub>(BR)CEO</sub>	40	-	Vdc	
Collector – Base Breakdown Voltage	(I <sub>C</sub> = 0.1 mAdc, I <sub>E</sub> = 0)	V <sub>(BR)CBO</sub>	60	-	Vdc	
Emitter-Base Breakdown Voltage	(I <sub>E</sub> = 0.1 mAdc, I <sub>C</sub> = 0)	V <sub>(BR)EBO</sub>	6.0	-	Vdc	
Base Cutoff Current	(V <sub>CE</sub> = 35 Vdc, V <sub>EB</sub> = 0.4 Vdc)	I <sub>BEV</sub>	-	0.1	μAdc	
Collector Cutoff Current	(V <sub>CE</sub> = 35 Vdc, V <sub>EB</sub> = 0.4 Vdc)	ICEX	-	0.1	μAdc	
ON CHARACTERISTICS (Note 3)	•					
DC Current Gain		hFE	20 40 80 100 40	- - 300 -	_	
Collector - Emitter Saturation Voltage	(I <sub>C</sub> = 150 mAdc, I <sub>B</sub> = 15 mAdc) (I <sub>C</sub> = 500 mAdc, I <sub>B</sub> = 50 mAdc)	V <sub>CE(sat)</sub>		0.4 0.75	Vdc	
Base – Emitter Saturation Voltage	( $I_C$ = 150 mAdc, $I_B$ = 15 mAdc) ( $I_C$ = 500 mAdc, $I_B$ = 50 mAdc)	V <sub>BE(sat)</sub>	0.75 -	0.95 1.2	Vdc	
SMALL-SIGNAL CHARACTERISTIC	S					
Current-Gain - Bandwidth Product	$(I_{C} = 20 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 100 \text{ MHz})$	f <sub>T</sub>	250	-	MHz	
Collector-Base Capacitance	$(V_{CB} = 5.0 \text{ Vdc}, I_E = 0, f = 1.0 \text{ MHz})$	C <sub>cb</sub>	-	6.5	pF	
Emitter-Base Capacitance	$(V_{EB} = 0.5 \text{ Vdc}, I_C = 0, f = 1.0 \text{ MHz})$	C <sub>eb</sub>	-	30	pF	
Input Impedance $(I_C = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz})$		h <sub>ie</sub>	1.0	15	kΩ	
/oltage Feedback Ratio $(I_{C} = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz})$		h <sub>re</sub>	0.1	8.0	X 10 <sup>-4</sup>	
Small-Signal Current Gain	$(I_{C} = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz})$	h <sub>fe</sub>	40	500	-	
Output Admittance	tput Admittance $(I_{C} = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz})$			30	μmhos	
SWITCHING CHARACTERISTICS						
Delay Time	(V <sub>CC</sub> = 30 Vdc, V <sub>EB</sub> = 2.0 Vdc,	t <sub>d</sub>	-	15		
Rise Time	$I_{\rm C} = 150 \text{ mAdc}, I_{\rm B1} = 15 \text{ mAdc})$	t <sub>r</sub>	-	20	ns	
Storage Time	(V <sub>CC</sub> = 30 Vdc, I <sub>C</sub> = 150 mAdc,	ts	-	225		
Fall Time	I <sub>B1</sub> = I <sub>B2</sub> = 15 mAdc)	t <sub>f</sub>	-	30	ns	

3. Pulse Test: Pulse Width  $\leq$  300 µs, Duty Cycle  $\leq$  2.0%.

## SWITCHING TIME EQUIVALENT TEST CIRCUITS

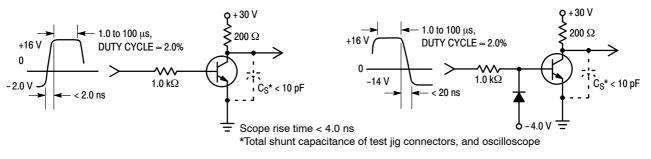


Figure 1. Turn-On Time

Figure 2. Turn-Off Time

#### **TRANSIENT CHARACTERISTICS**

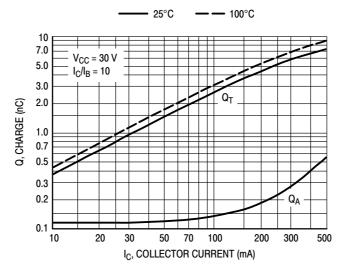
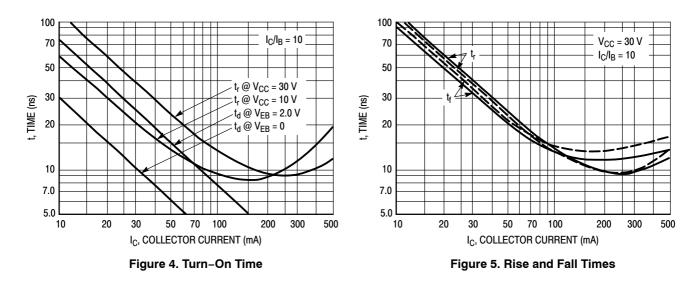
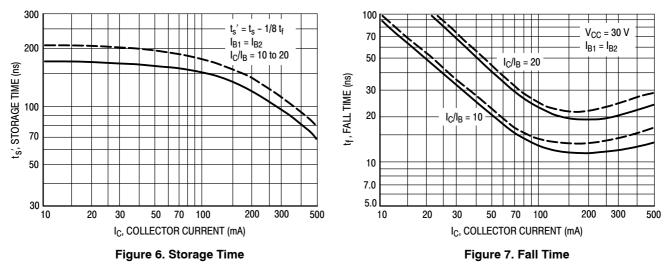
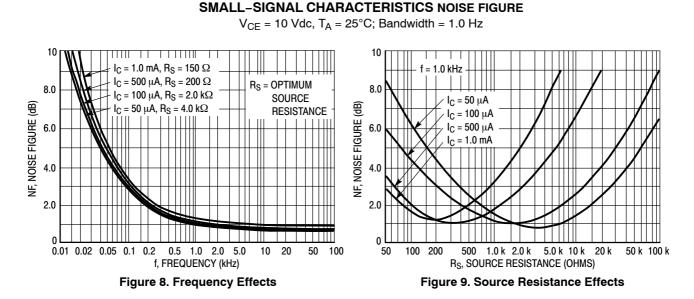


Figure 3. Charge Data



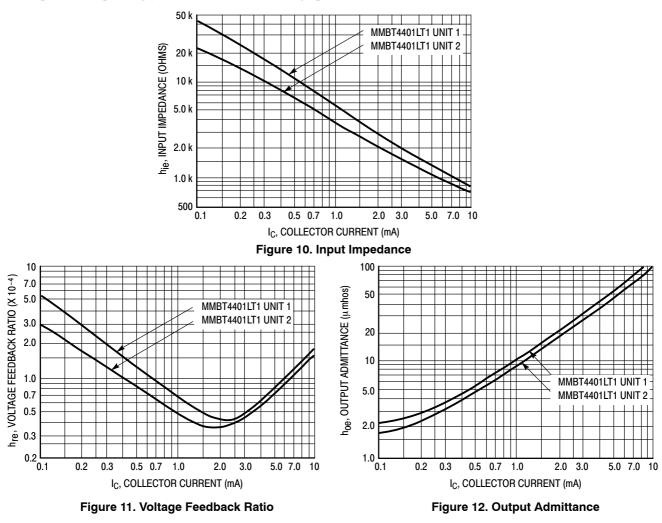




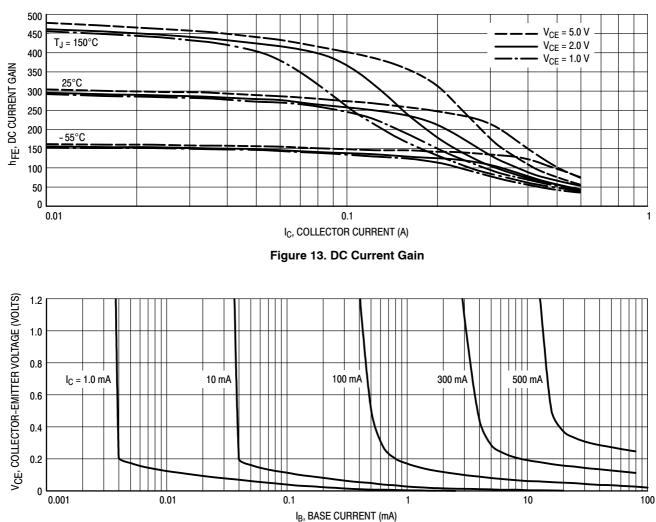
h PARAMETERS

 $V_{CE}$  = 10 Vdc, f = 1.0 kHz, T<sub>A</sub> = 25°C

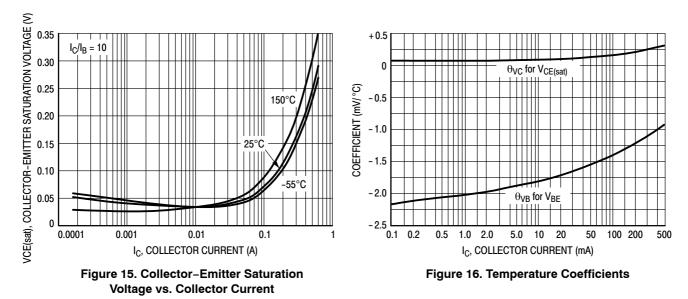
This group of graphs illustrates the relationship between  $h_{fe}$  and other "h" parameters for this series of transistors. To obtain these curves, a high–gain and a low–gain unit were selected from the MMBT4401LT1 lines, and the same units were used to develop the correspondingly numbered curves on each graph.



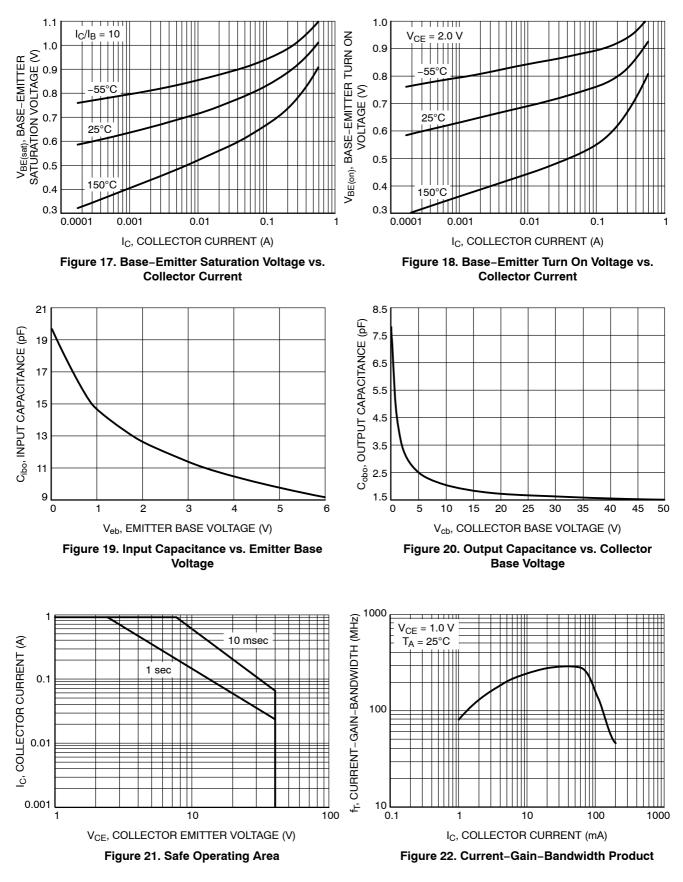
### **STATIC CHARACTERISTICS**





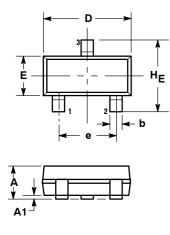


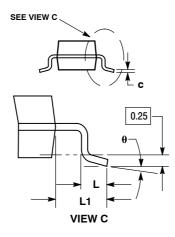
### STATIC CHARACTERISTICS



#### PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 ISSUE AN





NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF

BASE MATERIAL. 4. 318-01 THRU -07 AND -09 OBSOLETE,

4. 318-01 THRO -07 AND -09 OB301 NEW STANDARD 318-08.

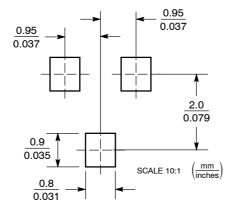
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
с	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 6:

PIN 1. BASE 2. EMITTER

3. COLLECTOR

**SOLDERING FOOTPRINT\*** 



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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